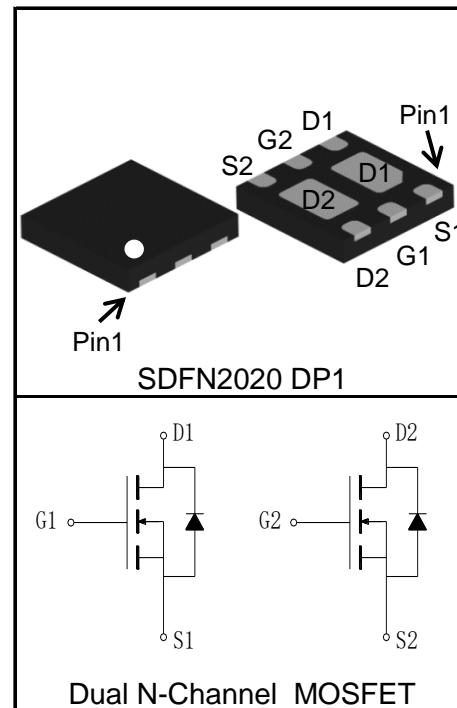


Features

- 20V/6A,
 $R_{DS(ON)} = 26m\Omega$ (Typ.)@ $V_{GS}=4.5V$
- $R_{DS(ON)} = 36m\Omega$ (Typ.)@ $V_{GS}=2.5V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

Pin Description



Applications

- Power Management
- Battery Protection



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_A=25^\circ C$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
I_S	Diode Continuous Forward Current	$T_A=25^\circ C$	A

Mounted on Large Heat Sink

$I_{DP}^{①}$	300 μ s Pulse Drain Current Tested	$T_A=25^\circ C$	24	A	
$I_D^{②}$	Continuous Drain Current($V_{GS}=4.5V$)	$T_A=25^\circ C$	6	A	
		$T_A=70^\circ C$	4.8		
P_D	Maximum Power Dissipation	$T_A=25^\circ C$	2.1	W	
		$T_A=70^\circ C$	1.3		
$R_{\theta JC}$	Thermal Resistance-Junction to Case	25	$^\circ C/W$		
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	60	$^\circ C/W$		

Drain-Source Avalanche Ratings

$E_{AS}^{④}$	Avalanche Energy, Single Pulsed	TBD	mJ
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Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KS2468UA2			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=250\mu\text{A}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V}$			1	μA
		$\text{T}_J=125^\circ\text{C}$			30	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	0.5	0.7	1.2	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$			± 100	nA
$\text{R}_{\text{DS}(\text{ON})}^{(5)}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=3\text{A}$		26	32	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_{\text{DS}}=2\text{A}$		36	46	$\text{m}\Omega$
Diode Characteristics						
$\text{V}_{\text{SD}}^{(5)}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=3\text{A}, \text{V}_{\text{GS}}=0\text{V}$		0.82	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{SD}}=3\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$		21		ns
Q_{rr}	Reverse Recovery Charge			9		nC
Dynamic Characteristics ⁽⁶⁾						
R_G	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$		1.4		Ω
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=10\text{V}, \text{Frequency}=1.0\text{MHz}$		600		pF
C_{oss}	Output Capacitance			115		
C_{rss}	Reverse Transfer Capacitance			85		
$\text{t}_{\text{d}(\text{ON})}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=10\text{V}, \text{I}_{\text{DS}}=3\text{A}, \text{V}_{\text{GEN}}=4.5\text{V}, \text{R}_G=6\Omega$		14		ns
t_r	Turn-on Rise Time			17		
$\text{t}_{\text{d}(\text{OFF})}$	Turn-off Delay Time			40		
t_f	Turn-off Fall Time			29		
Gate Charge Characteristics ⁽⁶⁾						
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=3\text{A}$		9.2		nC
Q_{gs}	Gate-Source Charge			1.2		
Q_{gd}	Gate-Drain Charge			2.4		

Notes:

- ①Pulse width limited by safe operating area.

- ②Calculated continuous current based on maximum allowable junction temperature.

- ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.

- ④Limited by $T_{J\max}$. Starting $T_J = 25^\circ\text{C}$.

- ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

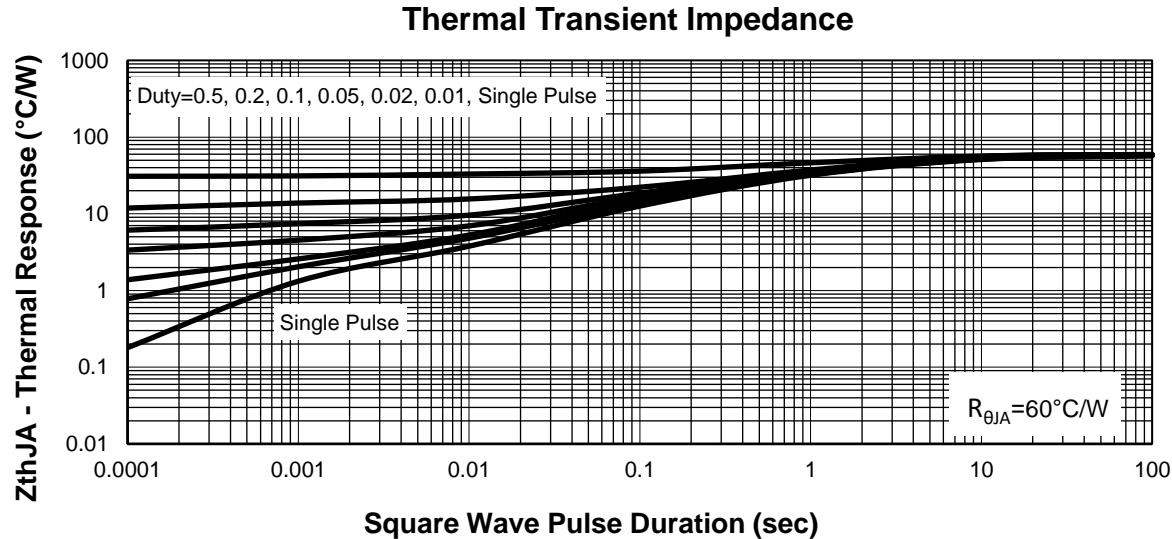
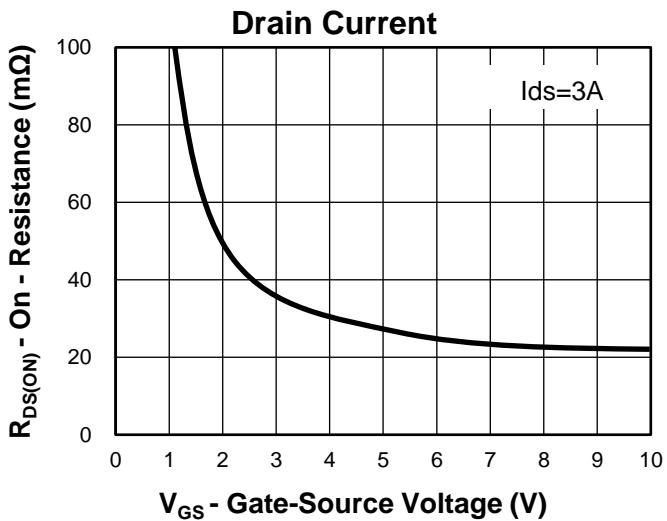
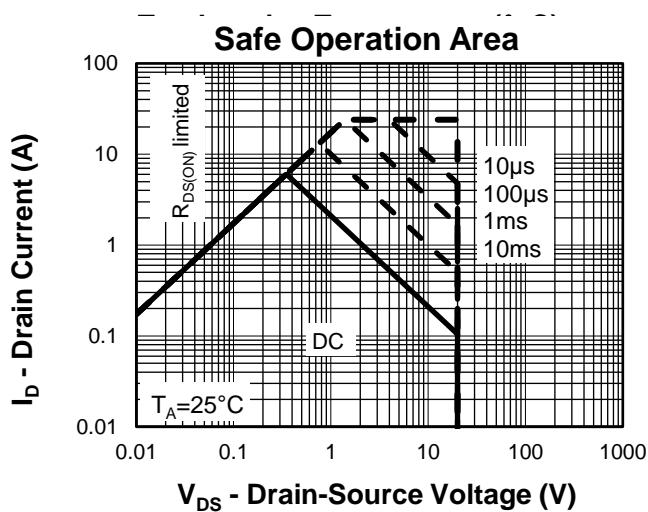
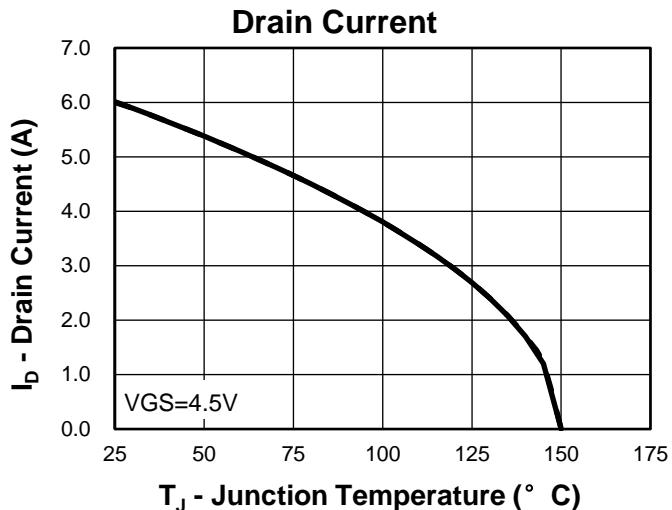
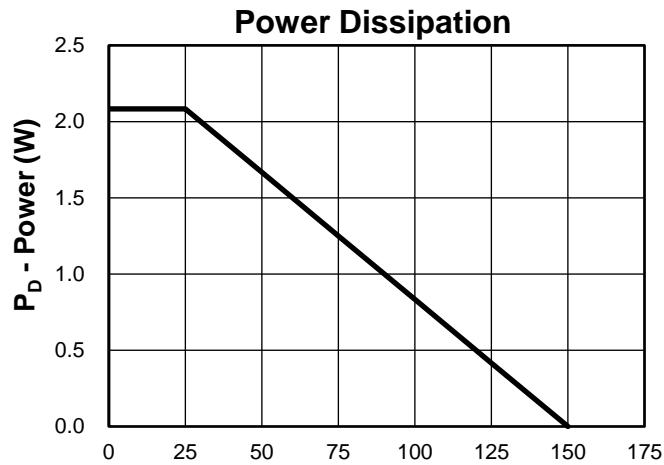
Device	Package	Packaging	Quantity	Reel Size	Tape width
KS2468UA2	SDFN2020 DP1	Tape&Reel	3000	7"	8mm



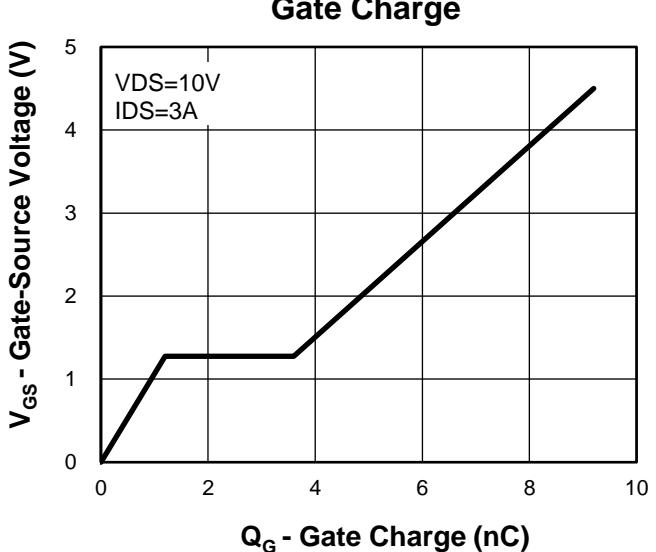
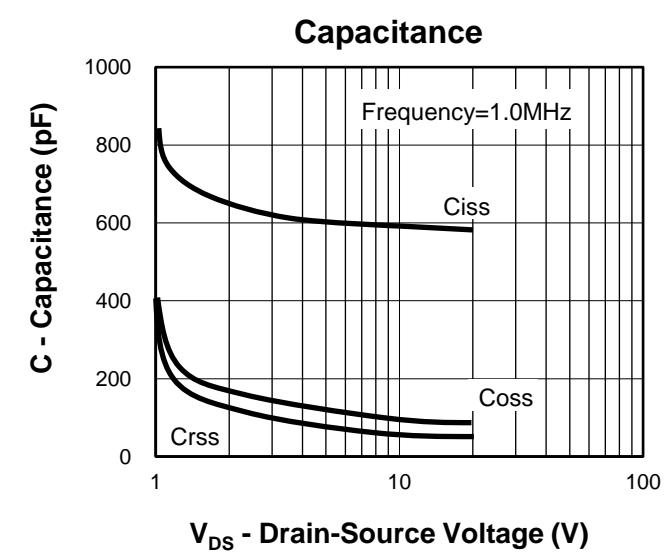
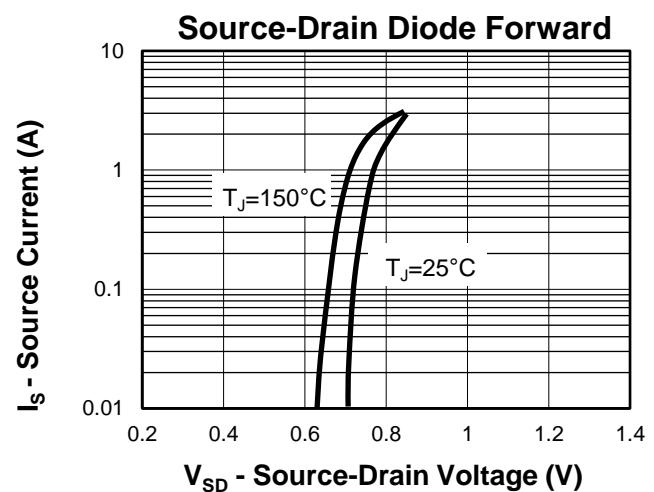
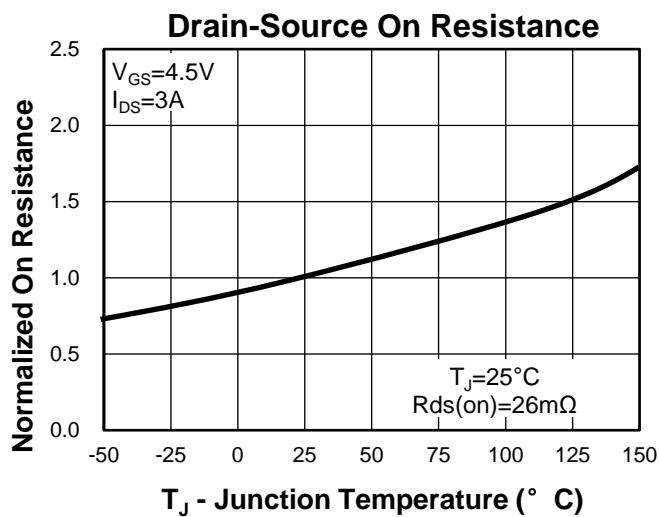
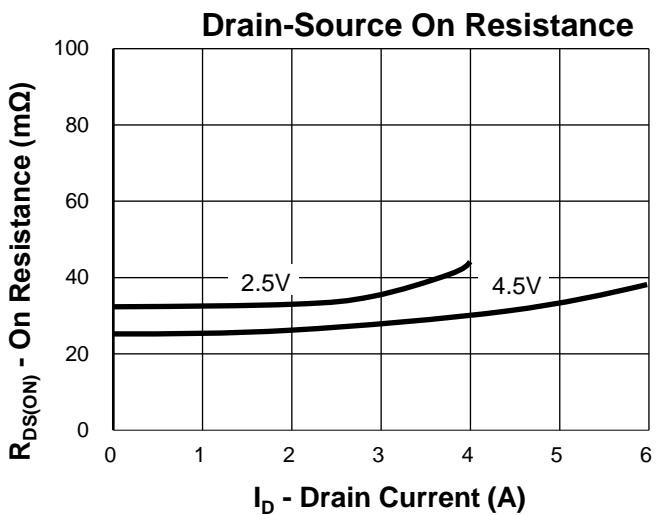
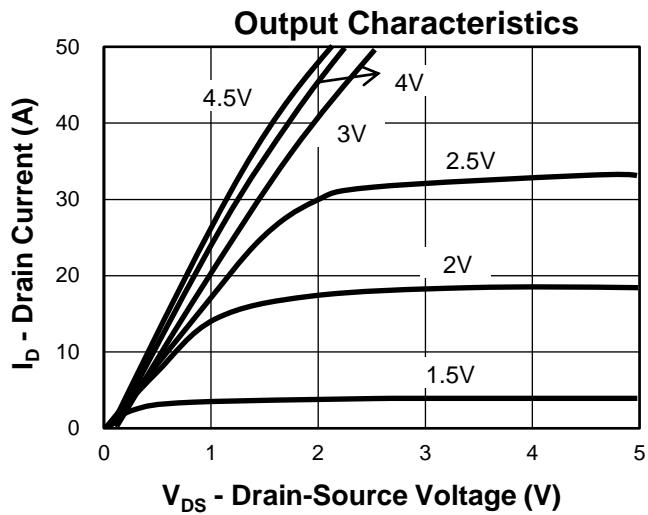
Y =Year,2017-A,2018-B,etc.

WW =Week.

Typical Characteristics

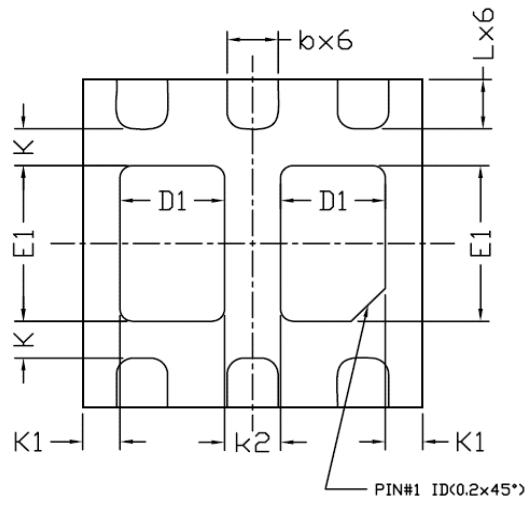
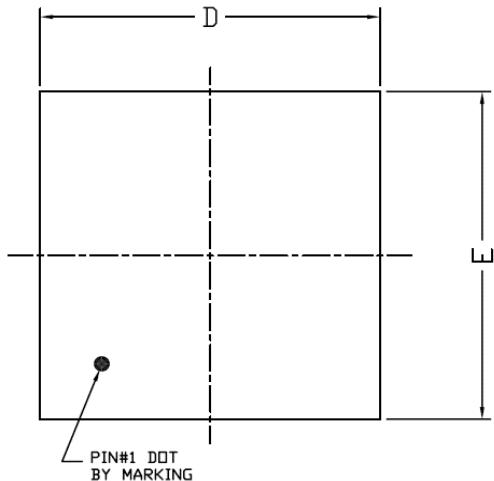


Typical Characteristics

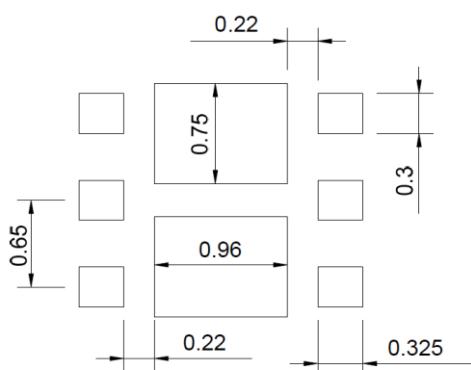
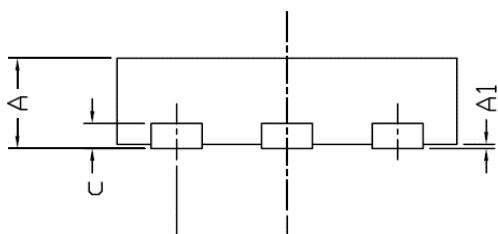


Package Information

SDFN2020 DP1



BOTTOM VIEW

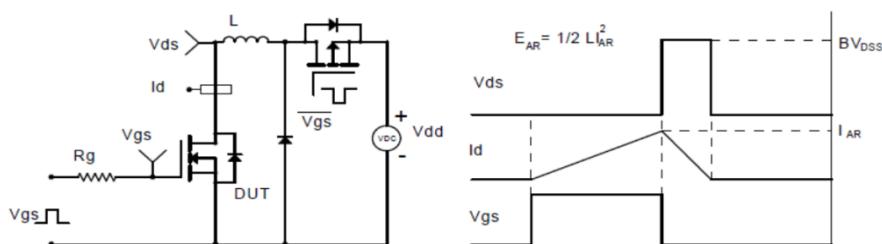


Land Pattern

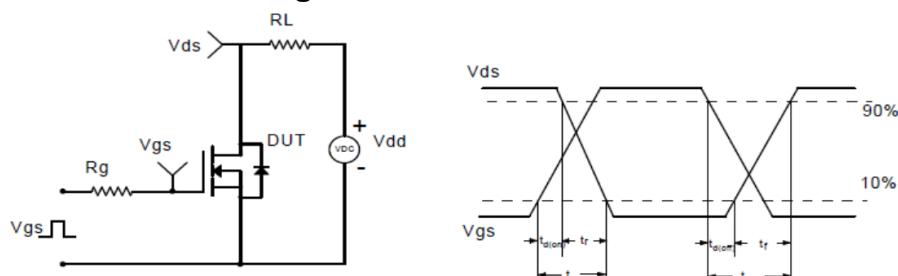
(Only for Reference)

SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.750	0.800	0.028	0.030	0.031
A1	0.000	0.020	0.050	0.000	0.001	0.002
b	0.225	0.275	0.325	0.009	0.011	0.013
c	0.203 REF.			0.008 REF.		
D	1.900	2.000	2.100	0.075	0.079	0.083
D1	0.500	0.550	0.600	0.020	0.022	0.024
E	1.900	2.000	2.100	0.075	0.079	0.083
E1	0.850	0.900	0.950	0.033	0.035	0.037
e	0.65 BSC			0.026 BSC		
K	0.25 BSC			0.001 BSC		
K1	0.22 BSC			0.009 BSC		
K2	0.40 BSC			0.016 BSC		
L	0.270	0.320	0.370	0.011	0.013	0.015

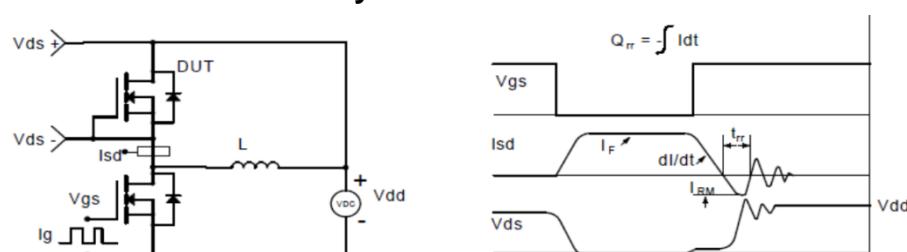
Avalanche Test Circuit and Waveforms



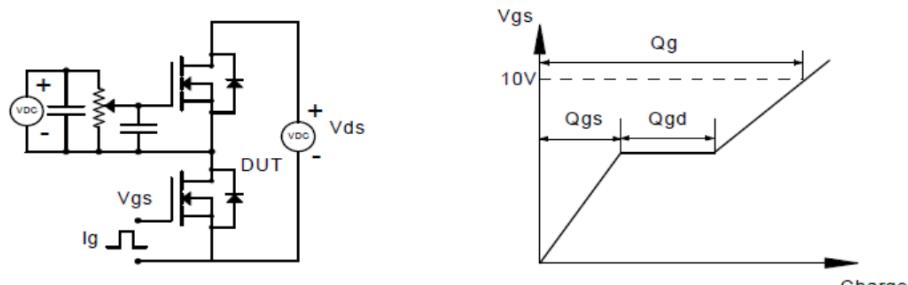
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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